

*Laser Debonding equipment
for large size panel*

SELD-LASER Series



Our series enable fast de-bonding process for large panel !

Equipment overview

This equipment is de-bonding equipment for separating carrier glass without stress by irradiating LASER.

Feature

Reducing damage to the device

The wavelength of the LASER is 355nm. LASER energy is absorbed in extreme thin layer of resin. Hence, it is possible to prevent device damage caused by LASER.

Applicable to large size panel

Panel size : Up to 600mm x 600mm

High speed de-bonding

By adopting high speed LASER system, high speed irradiation can be achieved compared to conventional scanner system.

Applicable to warpage

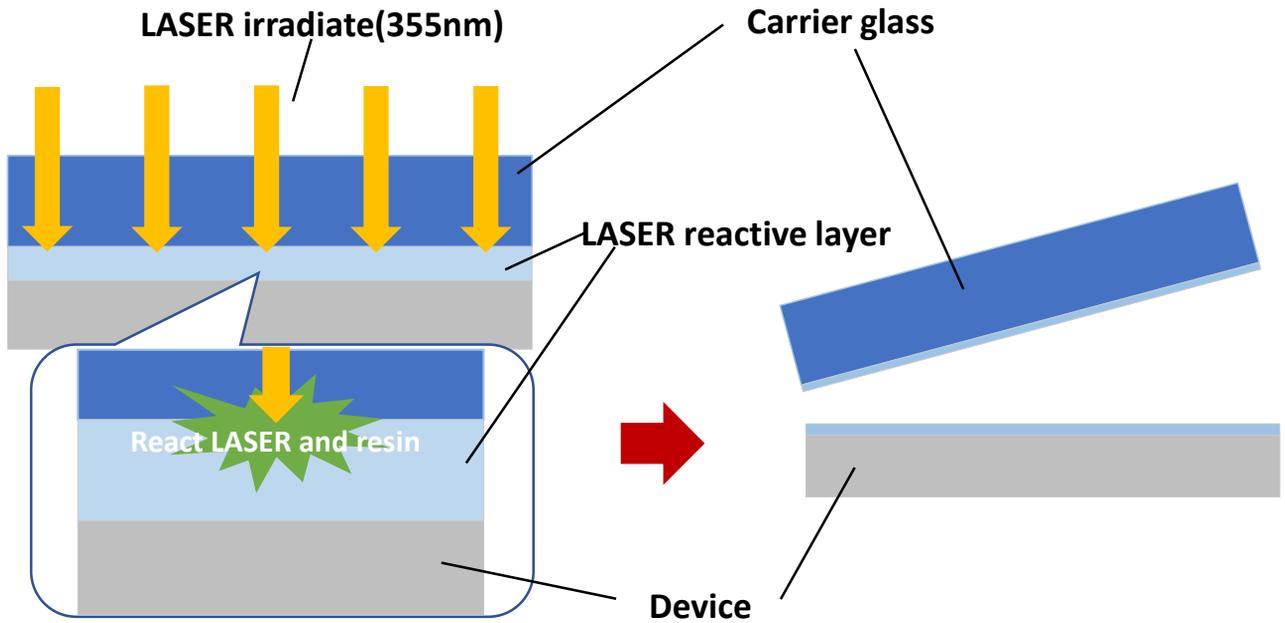
By adopting stable LASER beam against fluctuating in warpage, substrate with some warpage also can be de-bonded with stability. ("Stable LASER" means the evenness in beam figure, size, energy density)

Soot prevention after LASER irradiation

By introducing a dust remover, the soot is not scattered in the equipment, reducing its intrusion into the sliding part of the equipment.

※ **Licensed by IBM for laser de-bonding technology** ※

Processing flow(Model case)



LASER irradiate

Resin react

De-bond

仕様

Basic configuration	LASER generator、Scanner、Substrate stage、Chiller、Dust collector
Wave length	355nm(UV LASER)
Scan speed	>20m/s
Substrate applicable size	For panel size : Up to 600 × 600mm For wafer size : Up to φ300mm

ShinEtsu

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